

ABSTRACT

A epoxy resin composition includes a monofunctional epoxy compound having one epoxy group in a molecule thereof, a polyfunctional epoxy compound having two or more epoxy groups in a molecule thereof, and a curing agent. A curable resin composition includes a curable resin, a curing agent, and a compound having a (meth)acryloyl group. An electronic component device is provided with an element sealed with the epoxy resin composition or the curable resin composition.

[No suitable figure]